



Demonstration of a Low V_{ref} PA Based on InGaAsN Technology

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No Pain in GAIN!



This is NOT another GaN Talk

Gallium
+ Arsenic
+ Indium
+ Nitride

GAIN-HBT

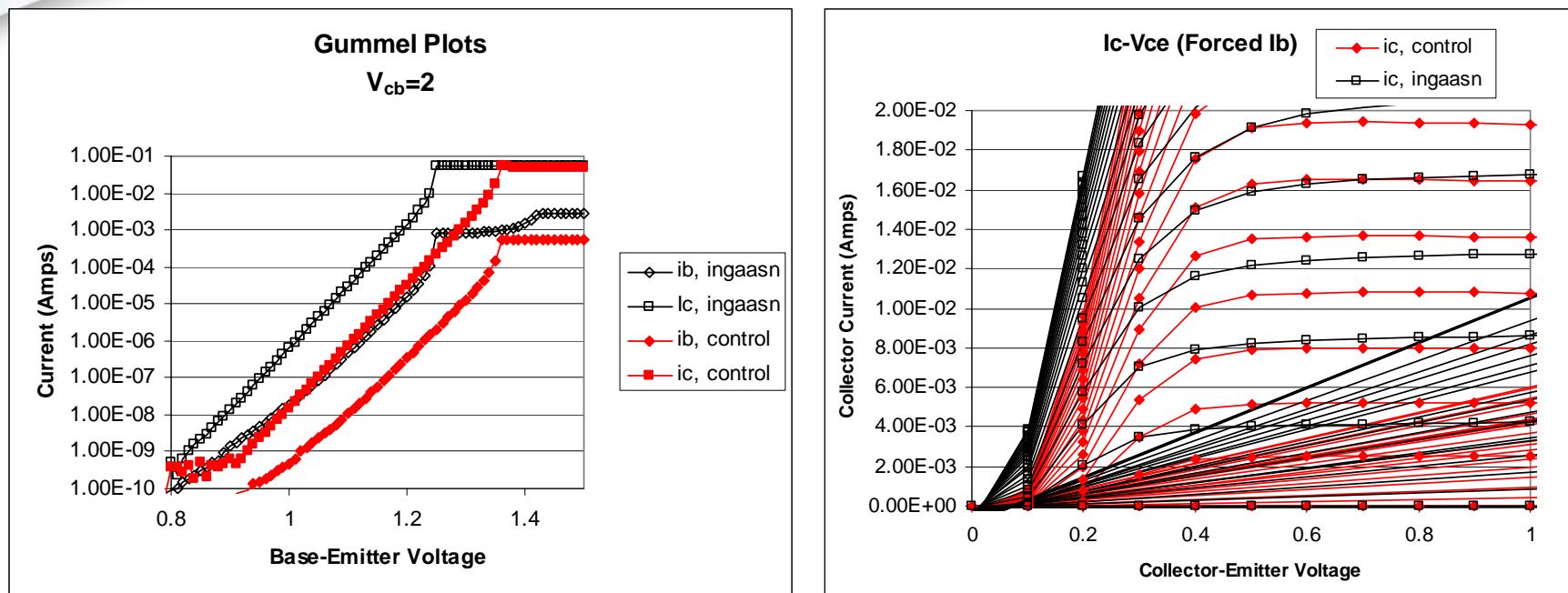
- What do we gain from GAIN?
 - Motivation for using dilute nitride GAIN-HBT™ material
- Device Level Characteristics
 - Reduction in turn-on voltage (100 mV)
 - Lower offset voltage (but does not correlate with PAE)
 - Softness in knee mitigated with adjustments to base-collector junction
 - Thinner base with compositional grade enhances f_t and f_{max}
- Circuit Results
 - Integrated PA fully functional at $V_{ref} = 2.6$ V and cold!
 - 2nd round of material with higher spacer doping improved performance
- Summary

GAIN-HBT™ is trademarked by Kopin Corporation

What do we gain from GAIN?

- The turn-on of an HBT is related to the base layer band gap
 - Addition of Indium (In) to GaAs Lowers the Band gap \Rightarrow Lower Turn-On
 - Nitrogen (N) Reduces Lattice Strain
- Typical Bias Circuits Use $2V_{be}$ \Rightarrow At Low V_{ref} & T This Chokes I_{ref}
 - Causes Circuit Performance to Fail at Cold for Low V_{ref}
- Using InGaAsN base (i.e. GAIN-HBT material) allows enough turn-on reduction (100 mV) to achieve device operation at $V_{ref}=2.6$ Volts and $T=-30$ C with less degradation to circuit performance
- Epi change only, *no fab re-tooling*

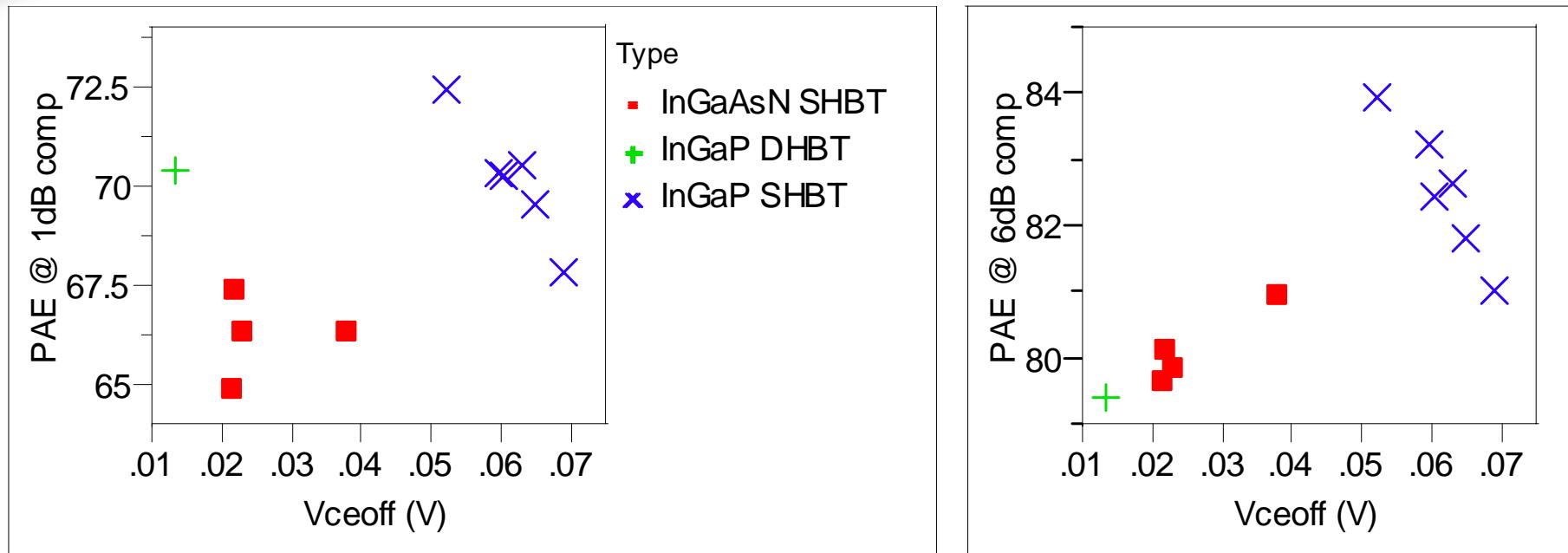
Device Characteristics



56 μm^2 Device

- Turn-on Improved by 0.1 Volts
- Off-set slightly improved (no real impact observed for circuit or RF performance, in general)
- Soft-knee (affecting ACP1) – like SiGe device – fixed in later rounds of material

$V_{ce,\text{offset}}$ Correlation Coefficients

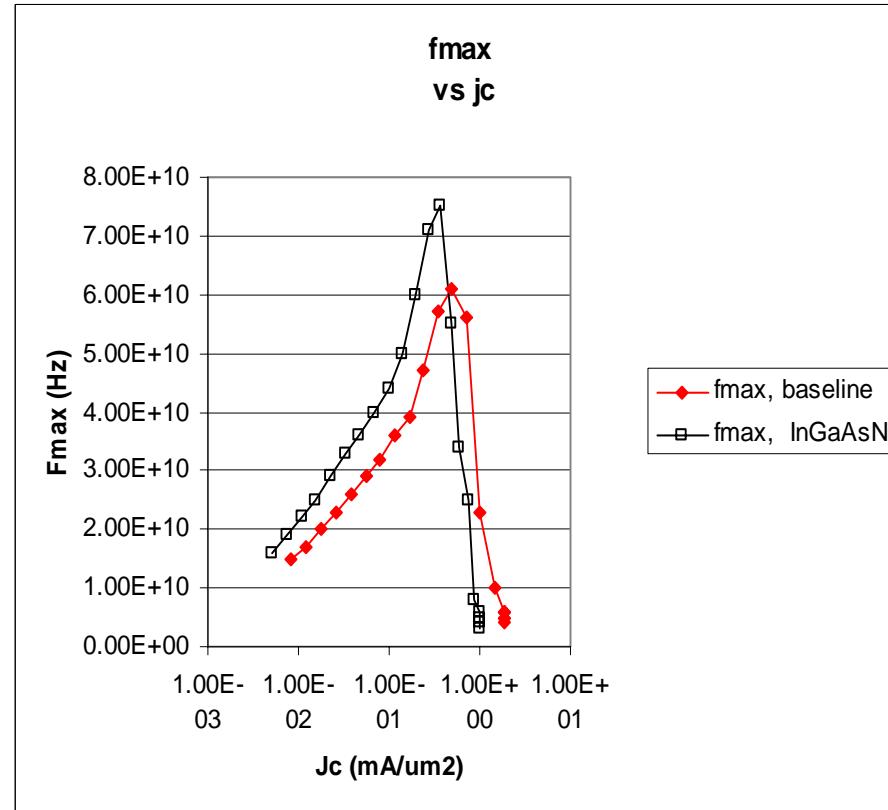
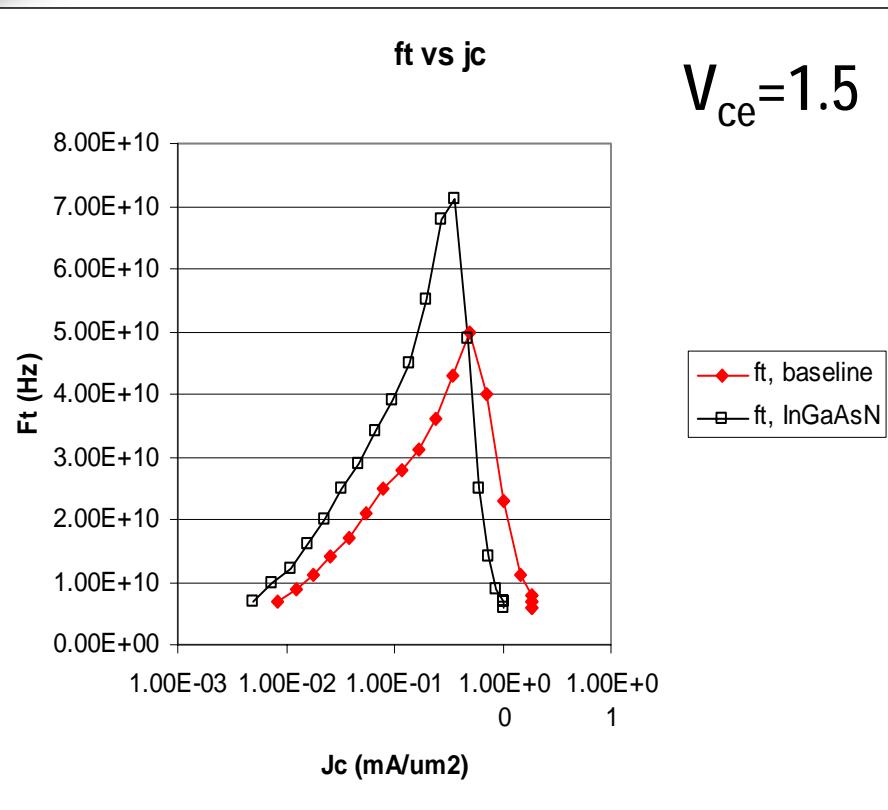


- No overall correlation between PAE and $V_{ce,\text{offset}}$
- Good correlation for InGaP SHBTs (no change in collector design)

Cristian Cismaru, et al, "Experimental Comparison of I_c - V_{ce} Parameters and Large-Signal Performance for III-V HBTs", BCTM 2005

Shameless Plug

InGaAsN AC Results



56 μm^2 Device

Improved AC performance due to thinner base and built-in field (40% thickness reduction)

Power Amplifier Test Results

- Part shown is designed for standard InGaP material
- InGaAsN material seamlessly substituted into a standard InGaP HBT process
- The PA was NOT RETUNED for InGaAsN material
- Material/Epi-specification accounts for ACP1, PAE degradation at higher V_{ref} (fixed in subsequent rounds of material)
- First Demonstration of a fully integrated InGaAsN HBT PA!

LoadPull ($V_{ref}=2.6V$, $P_{OUT}=28.0\text{dBm}$)

$V_{cc}=3.4V$, $V_{ref}=2.6V$, $T=25^{\circ}\text{C}$, $f_0=1.88\text{GHz}$, IS-95 modulation

ACPR1 Offset=1.25MHz, ACPR2 Offset =2.25MHz,
 Main Channel bandwidth=1.23MHz, Adjacent / Alternate channel bandwidth=30kHz

Type	$I_{cq}(\text{mA})$	$P_{out}(\text{dBm})$	ACPR1(dBc)	ACPR2(dBc)	PAE(%)	$P_{gain}(\text{dB})$
Control	38	28	49	55	41.4	25.6
Type	$I_{cq}(\text{mA})$	$P_{out}(\text{dBm})$	ACPR1(dBc) Max	ACPR2(dBc) Max	PAE(%) Max	$P_{gain}(\text{dB})$ Max
GalnNAs	94	28	45.4	61.2	47.2	25.8
Control	38	28	50.5	60.8	47.8	26.1

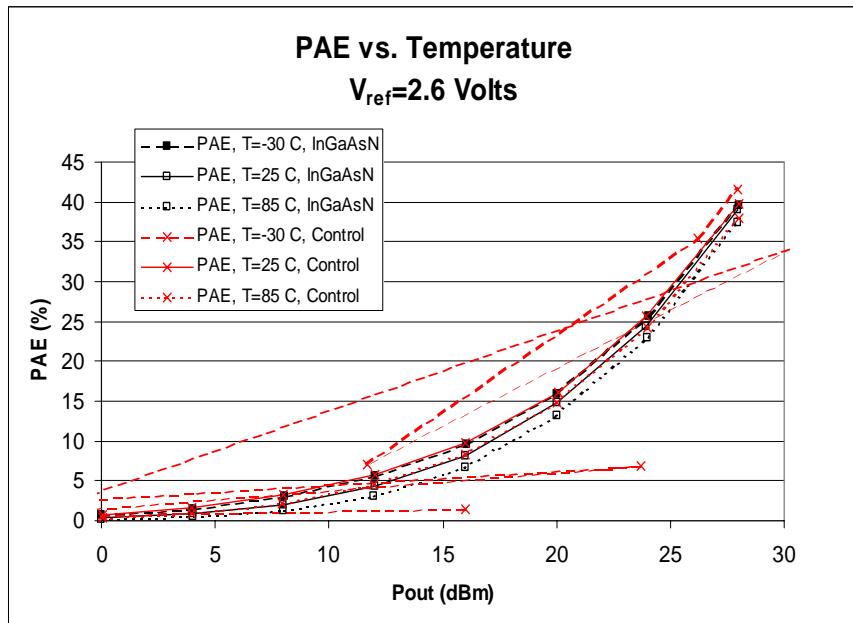
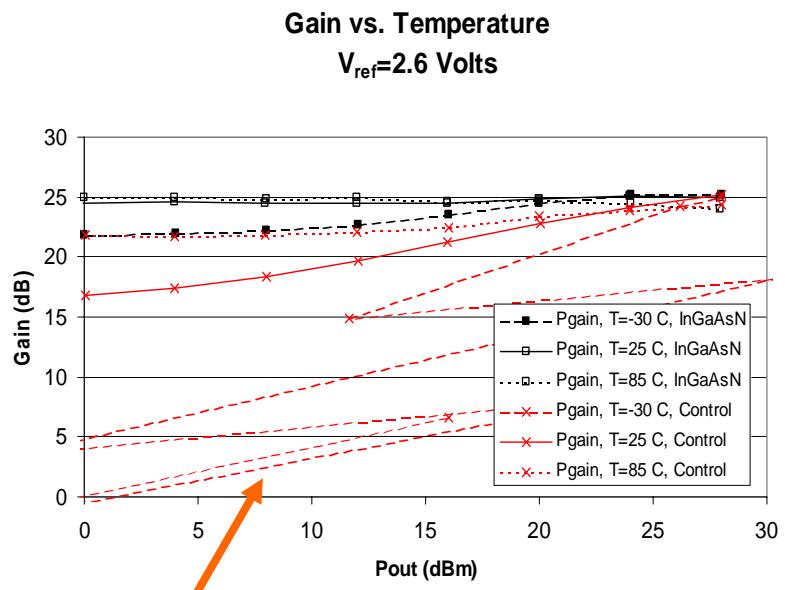
LoadPull ($I_{CQ}=95\text{mA}$, $P_{OUT}=28.0\text{dBm}$)

$V_{CC}=3.4V$, $I_{CQ}=95\text{mA}$, $T=25^{\circ}\text{C}$, $f_0=1.88\text{GHz}$, IS-95 modulation

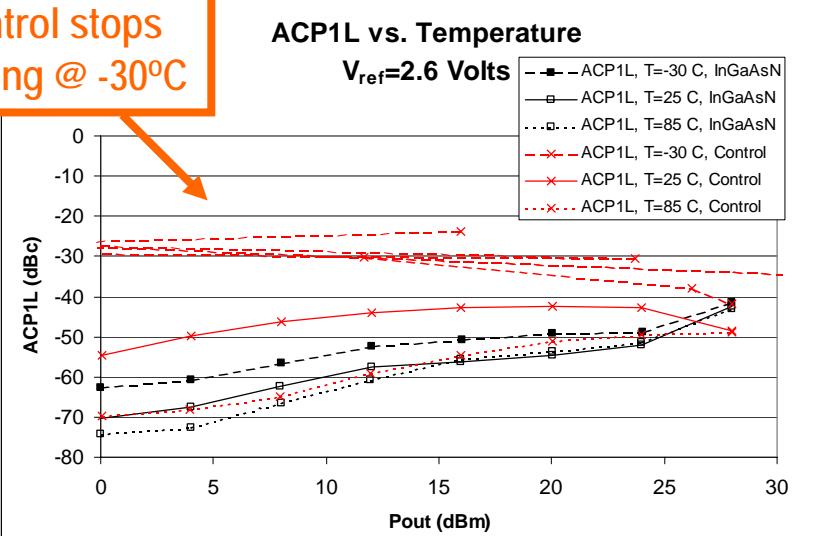
ACPR1 Offset=1.25MHz, ACPR2 Offset =2.25MHz,
 Main Channel bandwidth=1.23MHz, Adjacent / Alternate channel bandwidth=30kHz

Type	$I_{CQ}(\text{mA})$	$P_{out}(\text{dBm})$	ACPR1(dBc)	ACPR2(dBc)	PAE(%)	$P_{gain}(\text{dB})$
Control	95	28	49	58.9	39.8	27.1
Type	$I_{CQ}(\text{mA})$	$P_{out}(\text{dBm})$	ACPR1(dBc) Max	ACPR2(dBc) Max	PAE(%) Max	$P_{gain}(\text{dB})$ Max
GalnNAs	95	28	45.4	61.2	47.2	25.8
Control	95	28	52.3	63.2	46.6	27.3

$V_{ref}=2.6$ Volts, P_{gain} and PAE

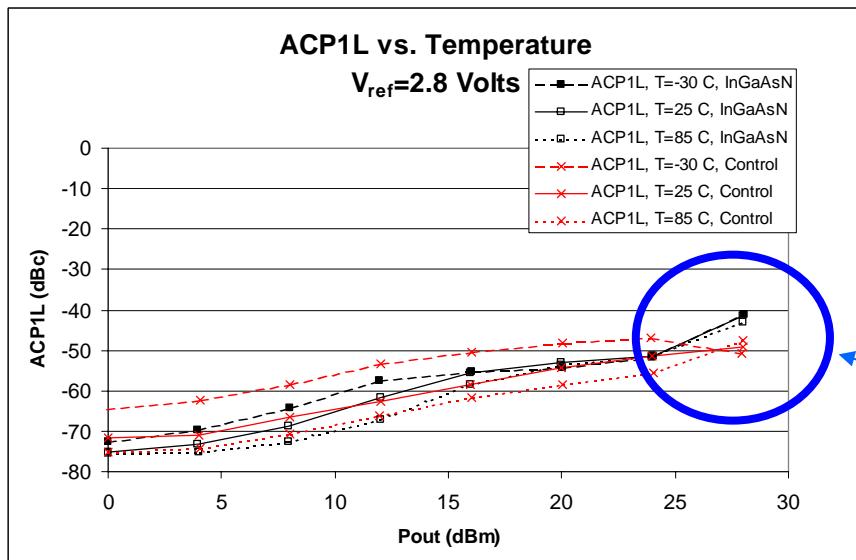
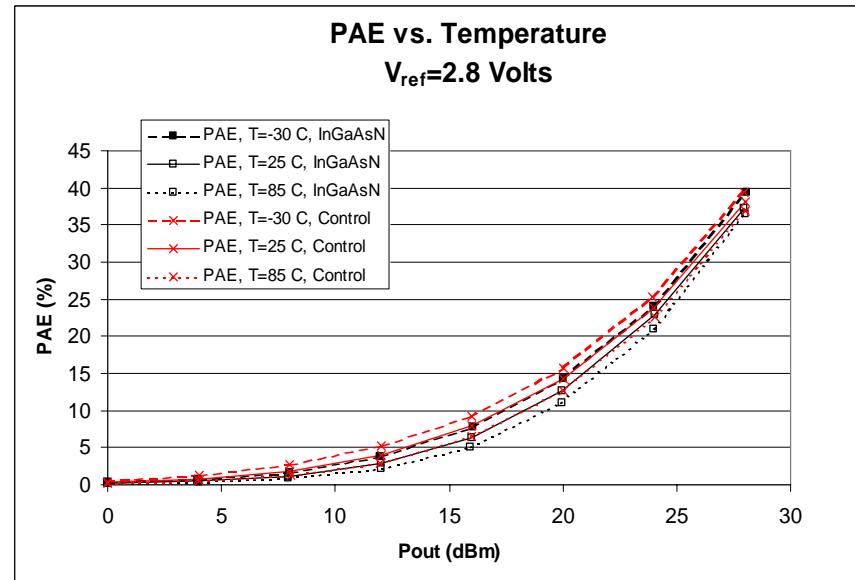
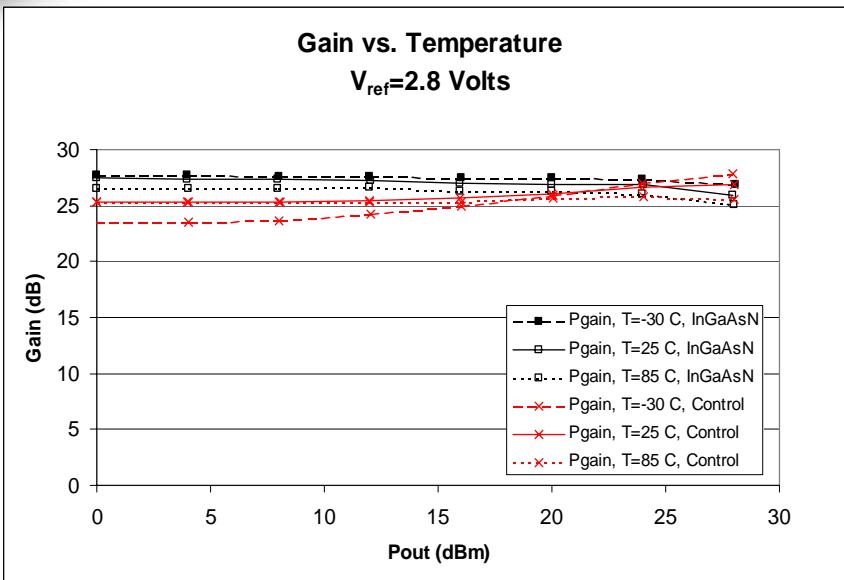


Control stops working @ -30°C



InGaAsN Part Functions
at 2.6 V_{ref} , Cold!

$V_{ref}=2.8$ Volts, P_{gain} and PAE

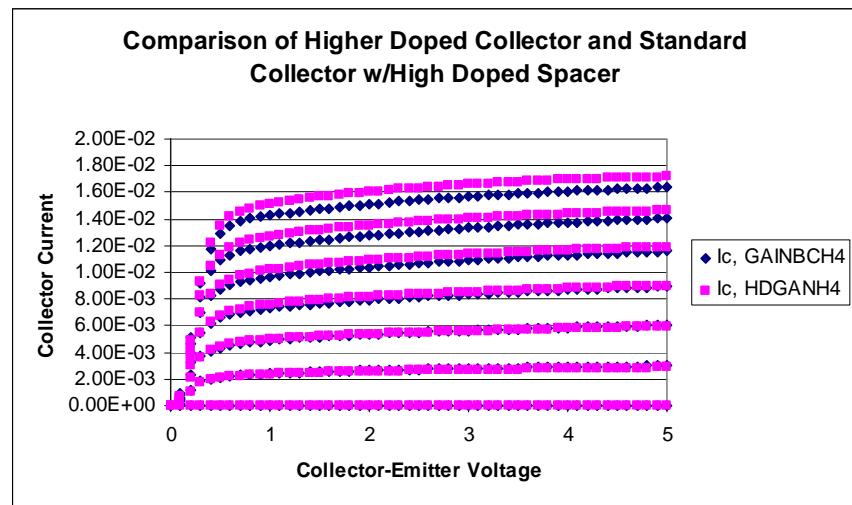
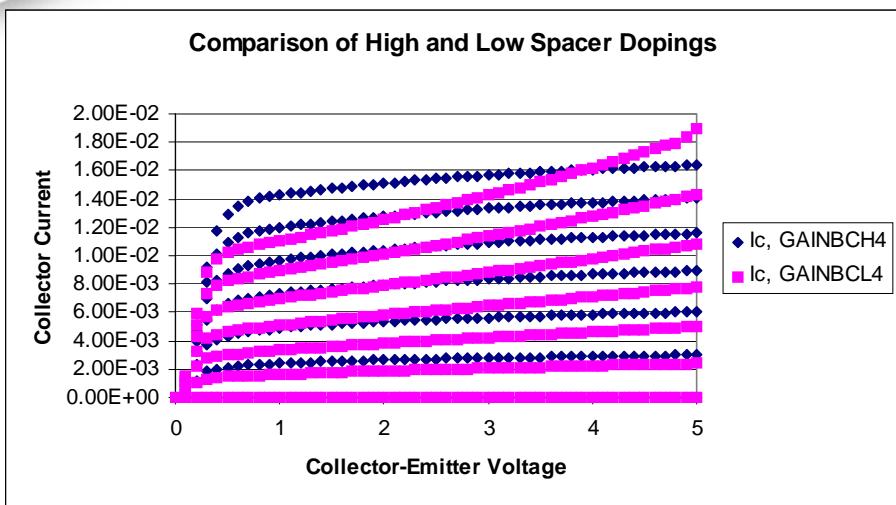


InGaAsN and control
comparable 2.8 V_{ref}

This is bad

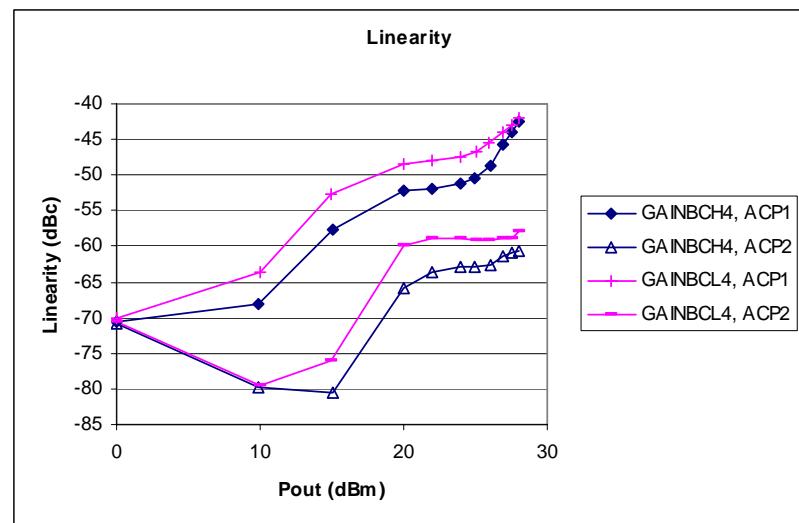
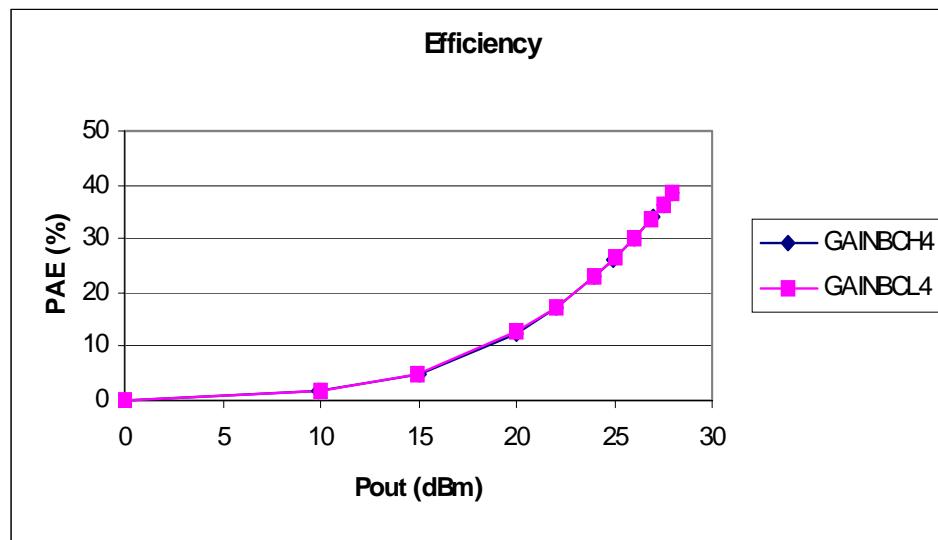
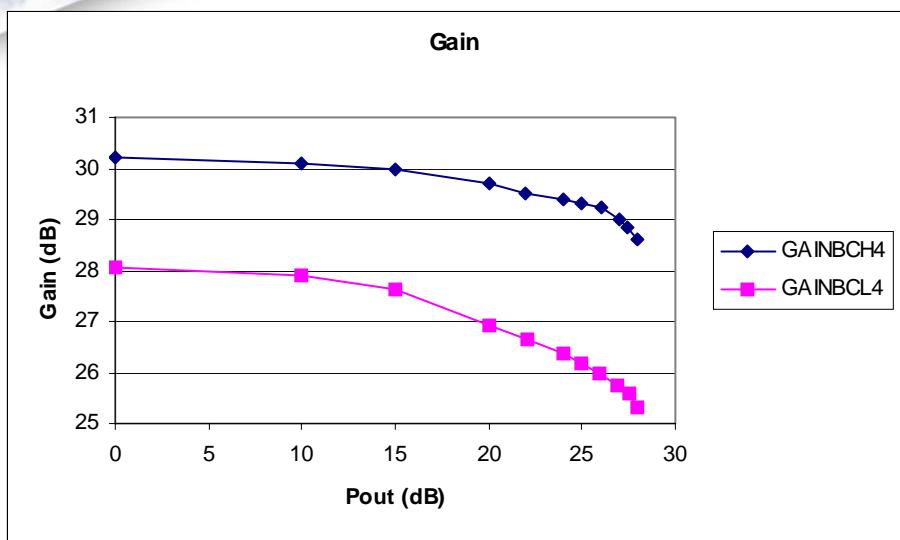
Device Level Experimental Results

2nd Generation Material



- Higher BC spacer doping improves knee voltage characteristics
- Results confirm performance degradation is due to low-doped spacer
- This has SIGNIFICANT impact on PA!

Effect of BC "Fix" on PA Performance, Different Part



GAINBCH4=high doped spacer
GAINBCL4=low doped spacer

As expected, higher doped spacer improved both Gain and Linearity

Summary and Status

- We have demonstrated a fully integrated PA that functions at a low V_{ref} (2.6 volts) at cold temperatures (-30 C)
 - 100 mV reduction is good enough for some applications
 - Some device level improvements did not translate to circuit level
- Second iteration material provided significant improvements
 - High doped spacer improves device level characteristics – observed effect was Early voltage, not barrier
 - High doped p+ spacer also improves gain and linearity over low-doped spacer
 - Some slight retuning was required (identical die) to implement in InGaAsN
- *GAIN material is being used in high volume commercial PAs!*

GAIN – It's not just for laundry anymore!



* Pick your acronyms carefully!